POWERTIP TECH. CORP.

SPECIFICATIONS

CUSTOMER	:	CUS999
SAMPLE CODE	:	SH240320T-063-L08Q
MASS PRODUCTION CODE	:	PH240320T-063-L08Q
SAMPLE VERSION	:	01
SPECIFICATIONS EDITION	:	003
DRAWING NO. (Ver.)	:	JLMD-PH240320T-063-L08Q_001
PACKAGING NO. (Ver.)	:	JPKG-PH240320T-063-L08Q_001

Customer Approved

Date:

POWERTIP
2015.11.23
JS RD APPROVED

Approved	Checked	Designer
閆偉	劉進	譚超敏

□ Preliminary specification for design input

■ Specification for sample approval

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History of Version

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
2012/12/25	01	001	New Drawing	-	趙冬冬
2013/03/05	01	002	New sample	-	趙冬冬
2015/05/05	01	003	Update Optical Characteristics	-	譚超敏

Total: 29 Page

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Note : For detailed information please refer to IC data sheet :
Primacy(TFT LCD): ILITEK: ILI9341

1. SPECIFICATIONS

1.1 Features

Main LCD panel

Item	Standard Value
Display Type	240(R、G、B) * 320 Dots
LCD Type	Normally white , Transmissive type
Screen size(inch)	2.8 inch
Viewing Direction	12 O'clock
Color configuration	RGB-Strip
Backlight	LED Backlight
Interface	MCU parallel / RGB / SPI
Other(controller/driver IC)	ILITEK: ILI9341
ROHS	THIS PRODUCT CONFORMS THE ROHS OF PTC Detail information please refer web side : http://www.powertip.com.tw/news.php?area_id_view=1085560481/

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	50.0(W) * 69.2 (L) * 3.05 (H)max	mm

LCD panel

Item	Standard Value	Unit
Active Area	43.2 (W) * 57.6 (L)	mm

1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit
System Power Supply Voltage	VDDI	-	-0.3	+4.6	V
	VGH ~ VGL	-	-0.3	+32	V
Input Voltage	VIN	-	-0.3	VDDI+0.3	V
Operating Temperature	T_{OP}	-	-20	+70	°C
Storage Temperature	T_{ST}	-	-30	+80	°C
Storage Humidity	H_D	Ta ≦ 60 °C	20	90	%RH

1.4 DC Electrical Characteristics

Module VSS = 0V, Ta = 25°C

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Power Supply Voltage1	VDDI	-	-	2.8	-	V
Input High Voltage	V_{IH}	-	0.7*VDDI	-	VDDI	V
Input Low Voltage	V_{IL}	-	VSS	-	0.3*VDDI	V
Output High Voltage	V_{OH}	I_{OH}=-0.1mA	0.8*VDDI	-	VDDI	V
Output Low Voltage	V_{OL}	I_{OL}=0.1mA	VSS	-	0.2*VDDI	V
Supply Current	IDD	VDDI = 2.8V Pattern= Black *1	-	9.4	14.5	mA

Note1:Maximum current display

1.5 Optical Characteristics

TFT LCD Module VDDI = 2.8V, Ta=25°C

Item		Symbol	Condition	Min.	Typ.	Max.	unit	-
Response time		Tr+ Tf	Ta = 25°C θX, θY = 0°	-	31	47	ms	Note2
Viewing angle	Top	θY+	CR ≥ 10	-	60	-	Deg.	Note4
	Bottom	θY-		-	60	-		
	Left	θX-		-	60	-		
	Right	θX+		-	60	-		
Contrast ratio		CR	Ta = 25°C θX , θY = 0°	500	600	-	-	Note3
Color of CIE Coordinate (With B/L)	White	X	-	0.25	0.30	0.35	-	Note1
		Y		0.28	0.33	0.38		
	Red	X		0.58	0.63	0.68		
		Y		0.3	0.35	0.40		
	Green	X		0.29	0.34	0.39		
		Y		0.56	0.61	0.66		
	Blue	X		0.09	0.14	0.19		
		Y		0.02	0.07	0.12		
Average Brightness Pattern=white display (With B/L) *1		IV	IF=80 mA	230	255	-	cd/m2	
Uniformity (With B/L)*2		△B	IF=80 mA	70	-	-	%	

Note 1:

*1：△B=B(min) / B(max) * 100%

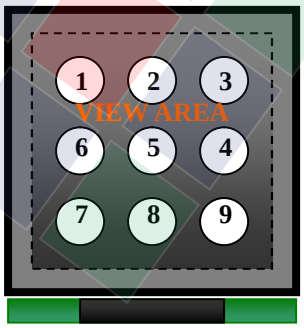
*2：Measurement Condition for Optical Characteristics:

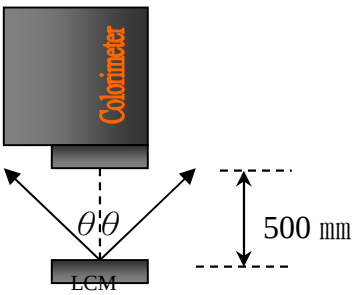
a：Environment: 25℃±5℃ / 60±20%R.H，no wind，dark room below 10 Lux at typical lamp current and typical operating frequency.

b：Measurement Distance: 500 ± 50 ㎜ ，(θ= 0°)

c：Equipment: TOPCON BM-7 fast，(field 1°)，after 10 minutes operation.

d：The uncertainty of the C.I.E coordinate measurement ±0.01，Average Brightness ± 4%





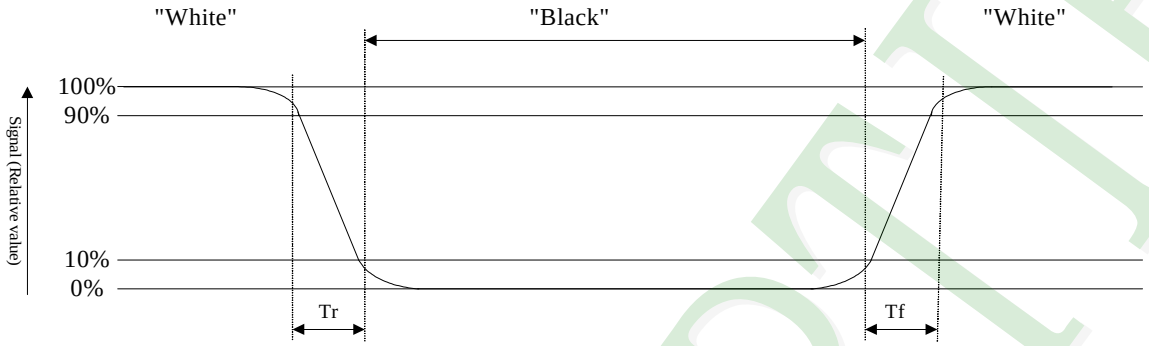
Colorimeter=BM-7 fast

To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)

Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from “black” to “white”(falling time) and from “white” to “black”(rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:



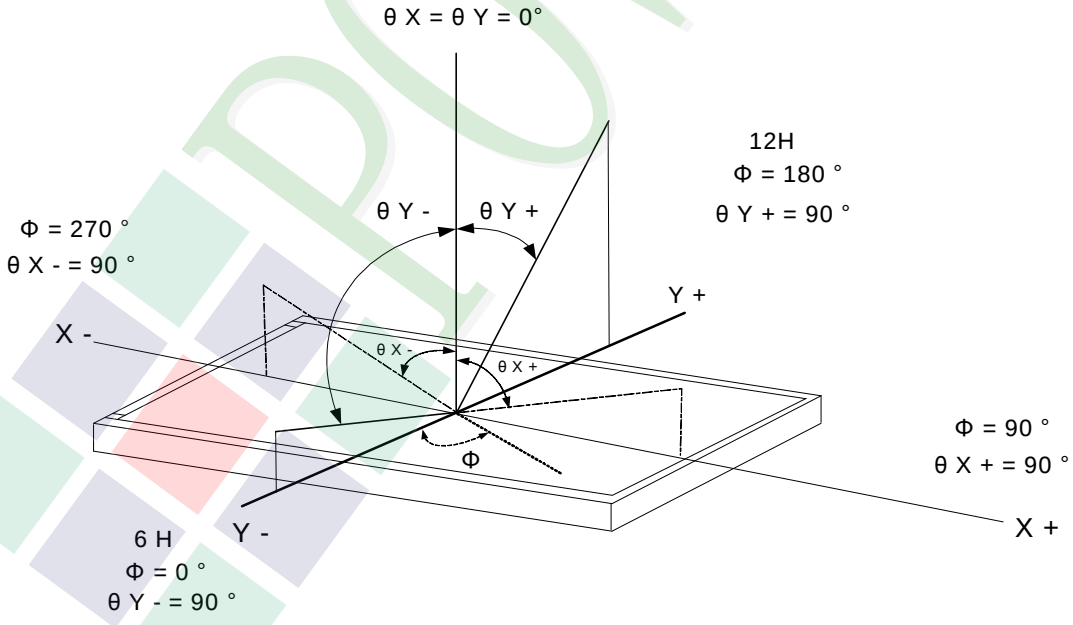
Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

$$\text{Contrast ratio (CR)} = \frac{\text{Photo detector output when LCD is at “White” state}}{\text{Photo detector output when LCD is at “Black” state}}$$

Note4: Definition of viewing angle:

Refer to figure as below:



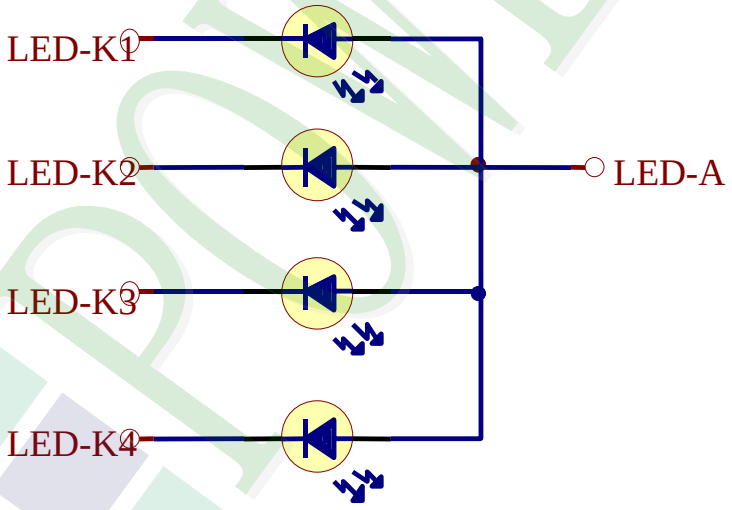
1.6 Backlight Characteristics

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Power Dissipation	PD	Ta =25℃	—	0.288	W

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Voltage	VF	IF= 80 mA	2.8	—	3.6	V
Average Brightness (without LCD)	IV		5000	5500	—	cd/m^2
CIE Color Coordinate (Without LCD)	X		0.26	0.28	0.33	-
	Y		0.26	0.28	0.33	
Color	White					

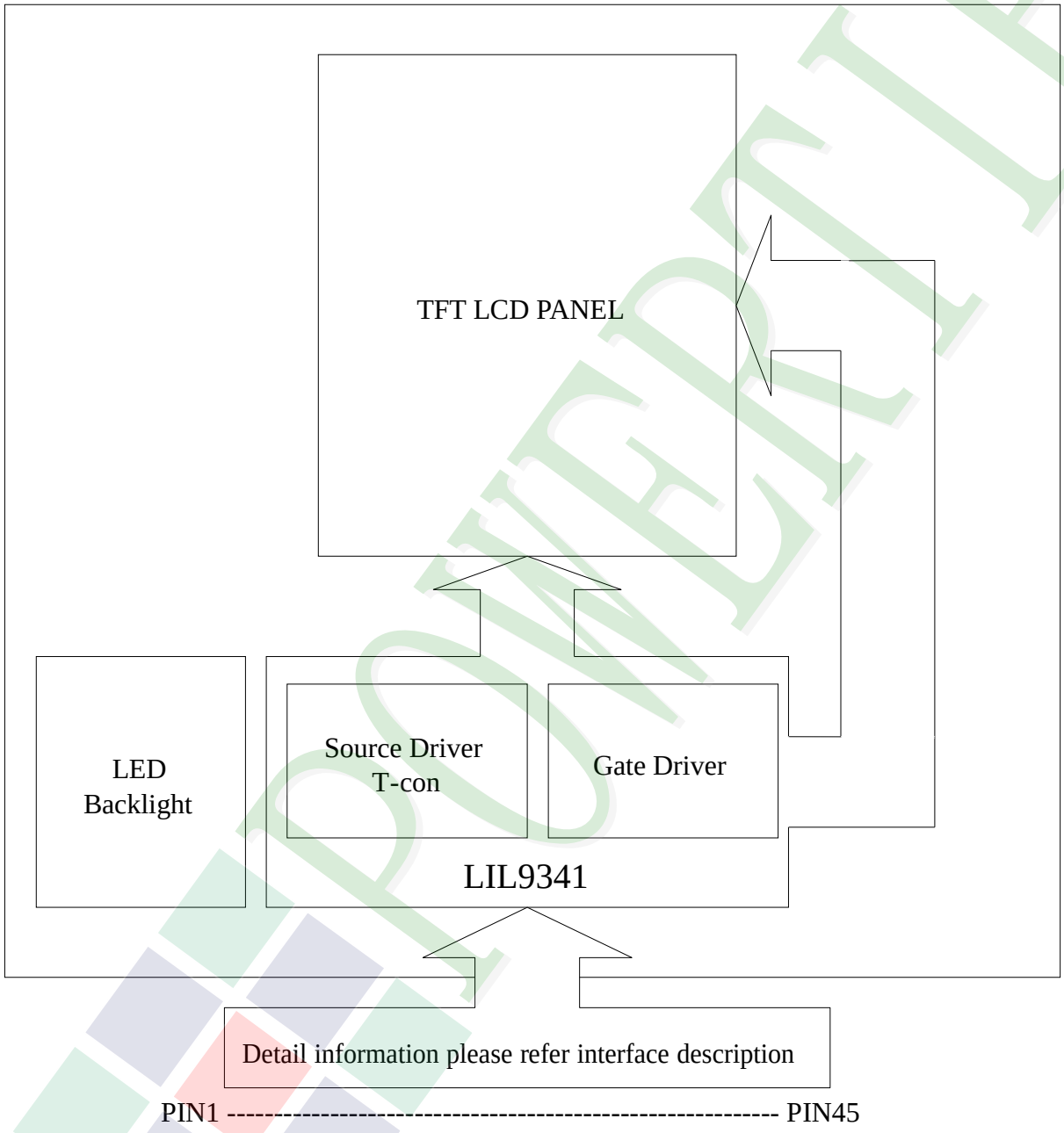


2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram



2.2 Interface Pin Description

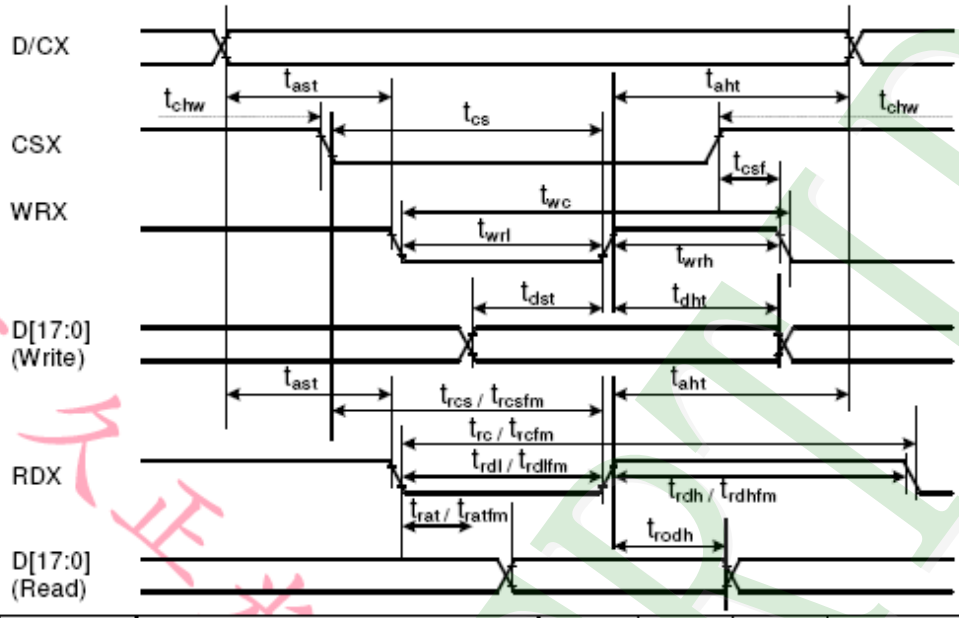
<table>
<tr><th>Pin No.</th><th>Symbol</th><th>Function</th></tr>
<tr><td>1</td><td>LED A</td><td>Backlight anode</td></tr>
<tr><td>2</td><td>LED K1</td><td>Backlight cathode</td></tr>
<tr><td>3</td><td>LED K2</td><td>Backlight cathode</td></tr>
<tr><td>4</td><td>LED K3</td><td>Backlight cathode</td></tr>
<tr><td>5</td><td>LED K4</td><td>Backlight cathode</td></tr>
<tr><td>6</td><td>IM0</td><td rowspan="4">- Select the MCU interface mode
<table>
<tr><th rowspan="2">IM3</th><th rowspan="2">IM2</th><th rowspan="2">IM1</th><th rowspan="2">IM0</th><th rowspan="2">MCU Interface Mode</th><th colspan="2">DB Pin in use</th></tr>
<tr><th>Register/Content</th><th>GRAM</th></tr>
<tr><td>0</td><td>0</td><td>0</td><td>0</td><td>80 MCU 8-bit bus interface I</td><td>D[7:0]</td><td>D[7:0]</td></tr>
<tr><td>0</td><td>0</td><td>0</td><td>1</td><td>80 MCU 16-bit bus interface I</td><td>D[7:0]</td><td>D[15:0]</td></tr>
<tr><td>0</td><td>0</td><td>1</td><td>0</td><td>80 MCU 9-bit bus interface I</td><td>D[7:0]</td><td>D[8:0]</td></tr>
<tr><td>0</td><td>0</td><td>1</td><td>1</td><td>80 MCU 18-bit bus interface I</td><td>D[7:0]</td><td>D[17:0]</td></tr>
<tr><td>0</td><td>1</td><td>0</td><td>1</td><td>3-wire 9-bit data serial interface I</td><td colspan="2">SDA: In/OUT</td></tr>
<tr><td>0</td><td>1</td><td>1</td><td>0</td><td>4-wire 8-bit data serial interface I</td><td colspan="2">SDA: In/OUT</td></tr>
<tr><td>1</td><td>0</td><td>0</td><td>0</td><td>80 MCU 16-bit bus interface II</td><td>D[8:1]</td><td>D[17:10], D[8:1]</td></tr>
<tr><td>1</td><td>0</td><td>0</td><td>1</td><td>80 MCU 8-bit bus interface II</td><td>D[17:10]</td><td>D[17:10]</td></tr>
<tr><td>1</td><td>0</td><td>1</td><td>0</td><td>80 MCU 18-bit bus interface II</td><td>D[8:1]</td><td>D[17:0]</td></tr>
<tr><td>1</td><td>0</td><td>1</td><td>1</td><td>80 MCU 9-bit bus interface II</td><td>D[17:10]</td><td>D[17:9]</td></tr>
<tr><td>1</td><td>1</td><td>0</td><td>1</td><td>3-wire 9-bit data serial interface II</td><td colspan="2">SDI: In
SDO: Out</td></tr>
<tr><td>1</td><td>1</td><td>1</td><td>0</td><td>4-wire 8-bit data serial interface II</td><td colspan="2">SDI: In
SDO: Out</td></tr>
</table>
MPU Parallel interface bus and serial interface select
If use RGB Interface must select serial interface.
* : Fix this pin at VDDI or VSS.</td></tr>
<tr><td>7</td><td>IM1</td></tr>
<tr><td>8</td><td>IM2</td></tr>
<tr><td>9</td><td>IM3</td></tr>
</table>

10	FMARK	Tearing effect output pin to synchronize MPU to frame writing, activated by S/W command. When this pin is not activated, this pin is low. If not used, open this pin
11	VSYNC	Frame synchronizing signal for RGB interface operation. Fix to VDDI or VSS level when not in use.
12	HSYNC	Line synchronizing signal for RGB interface operation. Fix to VDDI or VSS level when not in use.
13	DOTCLK	Dot clock signal for RGB interface operation. Fix to VDDI or VSS level when not in use.
14	ENABLE	Data enable signal for RGB interface operation. Fix to VDDI or VSS level when not in use.
15~32	DB17~DB0	18 bit parallel bi-direction data bus for MCU system and RGB interface mode. Fix to VSS level when not in use. Please refer to the IM[0:3] setting.
33	CS	This pin is used to select “Data or Command” in the parallel interface or 4-wire 8-bit serial data interface. When RS = ‘1’, data is selected. When RS = ‘0’, command is selected. This pin is used serial interface clock in 3-wire 9-bit / 4-wire 8-bit serial data interface. If not used, this pin should be connected to VDDI or VSS.
34	WR	- 8080-I / 8080-II system (WRX): Serves as a write signal and writes data at the rising edge. - 4-line system (D/CX): Serves as command or parameter select. Fix to VDDI or VSS level when not in use.
35	RS/SCL	This pin is used to select “Data or Command” in the parallel interface. When RS = ‘1’, data is selected. When RS = ‘0’, command is selected. This pin is used serial interface clock in 3-wire 9-bit / 4-wire 8-bit serial data interface. If not used, this pin should be connected to VDDI or VSS.
36	RD	8080-I / 8080-II system (RDX): Serves as a read signal and MCU read data at the rising edge. Fix to VDDI or VSS level when not in use.

37	RESET	Reset pin.
38	SDO	Serial output signal. The data is outputted on the falling edge of the SCL signal. If not used, open this pin
39	SDI	When IM[3] : Low, Serial in/out signal. When IM[3] : High, Serial input signal. The data is applied on the rising edge of the SCL signal. If not used, fix this pin at VDDI or VSS.
40	VDDI	Power supply 2.8V
41	GND	Power ground 0V
42	NC	No Connection
43	NC	
44	NC	
45	NC	

2.3 Timing Characteristics

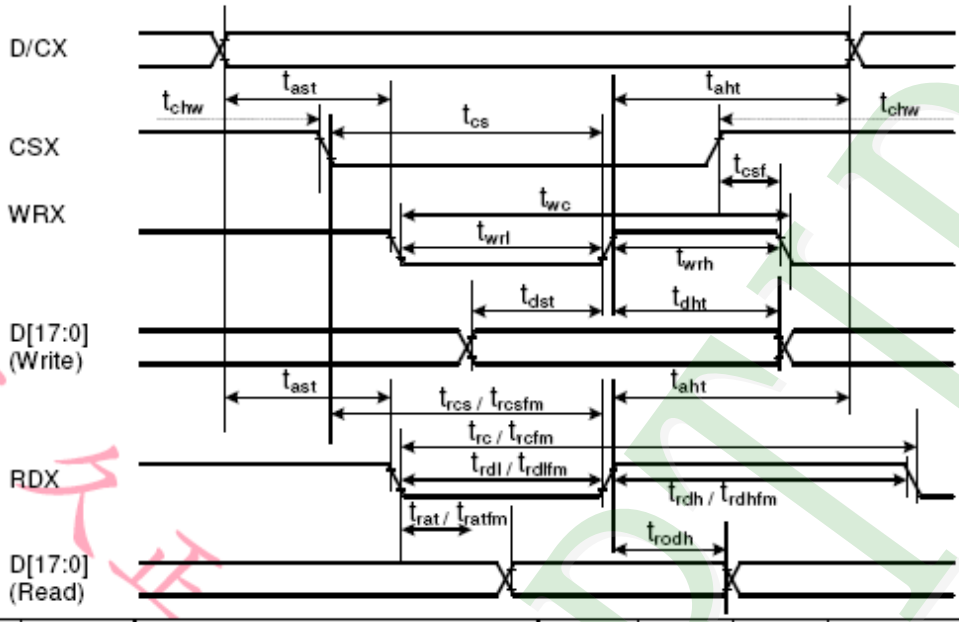
Display Parallel 18/16/9/8-bit Interface Timing Characteristics (8080- I system)



Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[15:0], D[8:0], D[7:0]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V

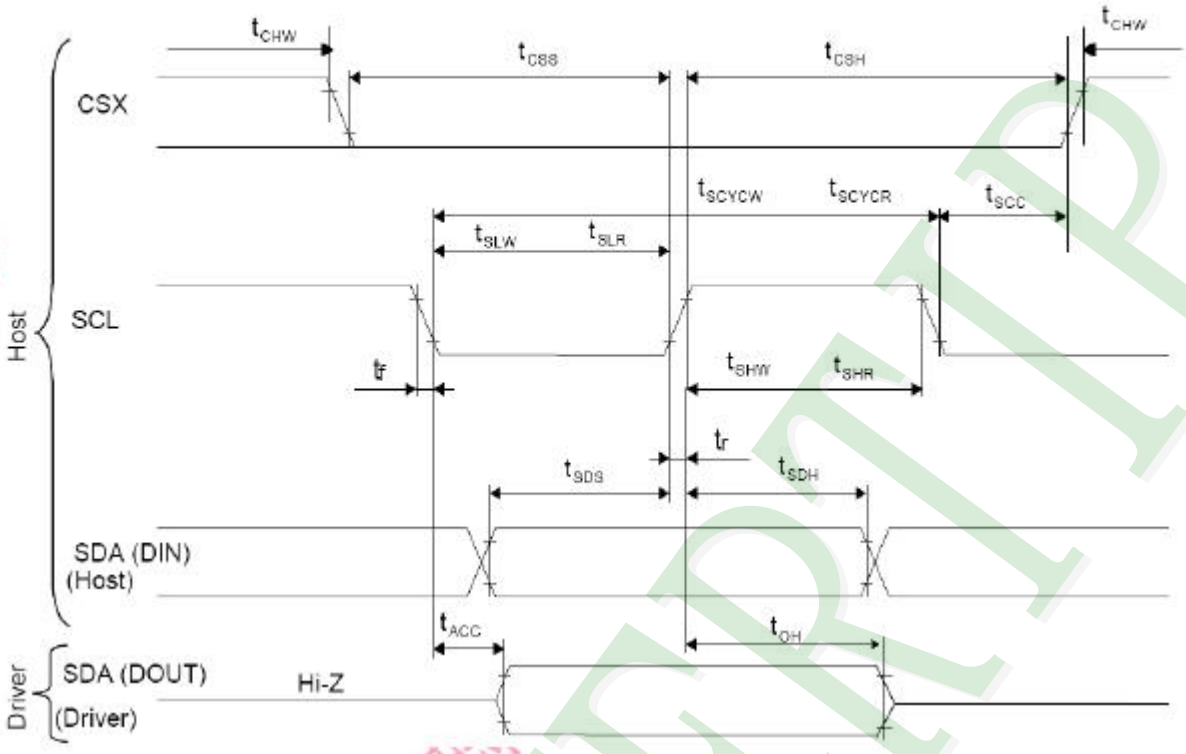
Display Parallel 18/16/9/8-bit Interface Timing Characteristics(8080-Ⅱ system)



Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[17:10]&D[8:1], D[17:10], D[17:9]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V.

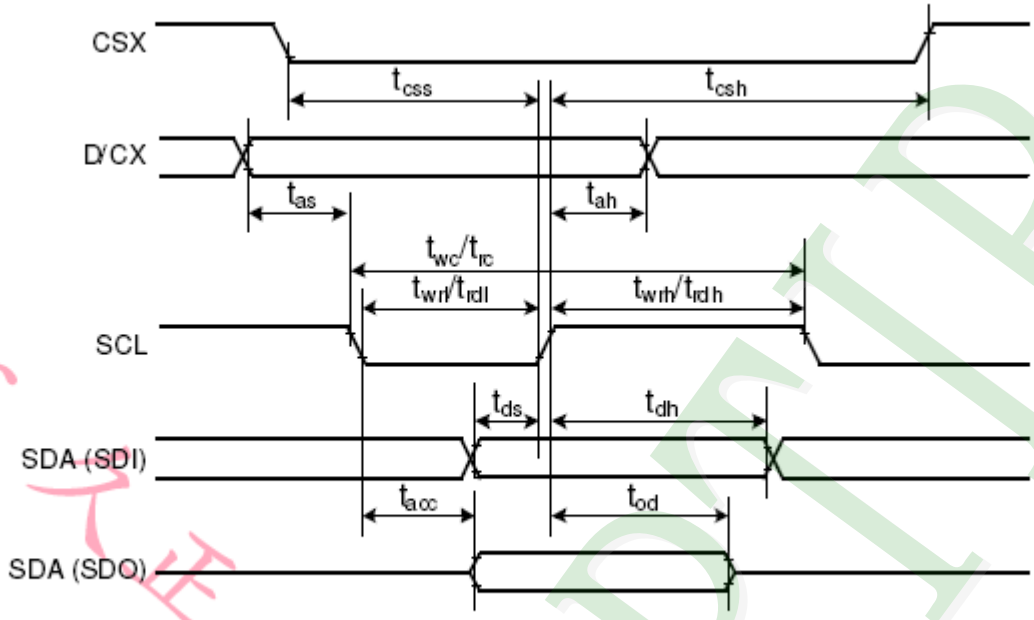
Display Serial Interface Timing Characteristics (3-line SPI system)



Signal	Symbol	Parameter	min	max	Unit	Description
SCL	tscycw	Serial Clock Cycle (Write)	100	-	ns	
	tshw	SCL "H" Pulse Width (Write)	40	-	ns	
	tslw	SCL "L" Pulse Width (Write)	40	-	ns	
	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL "H" Pulse Width (Read)	60	-	ns	
	tslr	SCL "L" Pulse Width (Read)	60	-	ns	
SDA / SDI (Input)	tsds	Data setup time (Write)	30	-	ns	
	tsdh	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	tacc	Access time (Read)	10	-	ns	
	toh	Output disable time (Read)	10	50	ns	
CSX	tscc	SCL-CSX	20	-	ns	
	tchw	CSX "H" Pulse Width	40	-	ns	
	tcss	CSX-SCL Time	60	-	ns	
	tcsh		65	-	ns	

Note: Ta = 25 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

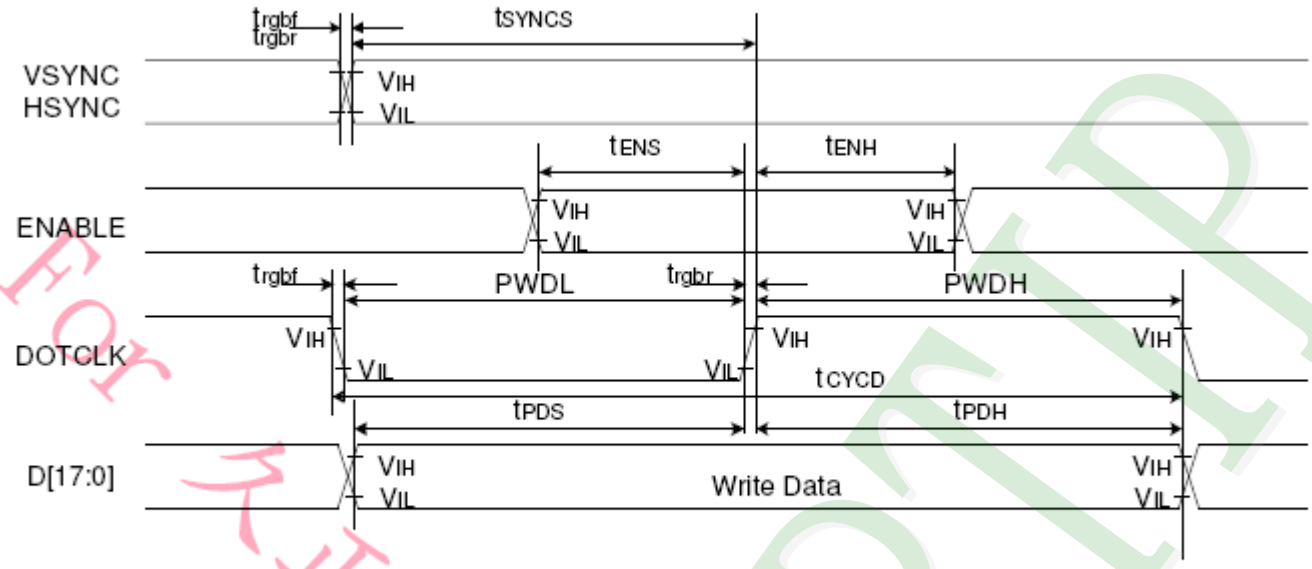
Display Serial Interface Timing Characteristics (4-line SPI system)



Signal	Symbol	Parameter	min	max	Unit	Description
CSX	tcss	Chip select time (Write)	40	-	ns	
	tcsh	Chip select hold time (Read)	40	-	ns	
SCL	twc	Serial clock cycle (Write)	100	-	ns	
	twrh	SCL "H" pulse width (Write)	40	-	ns	
	twrl	SCL "L" pulse width (Write)	40	-	ns	
	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL "H" pulse width (Read)	60	-	ns	
	trdl	SCL "L" pulse width (Read)	60	-	ns	
D/CX	tas	D/CX setup time	10	-		
	tah	D/CX hold time (Write / Read)	10	-		
SDA / SDI (Input)	tds	Data setup time (Write)	30	-	ns	
	tdh	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	tacc	Access time (Read)	10	-	ns	For maximum CL=30pF
	tod	Output disable time (Read)	10	50	ns	For minimum CL=8pF

Note: Ta = 25 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

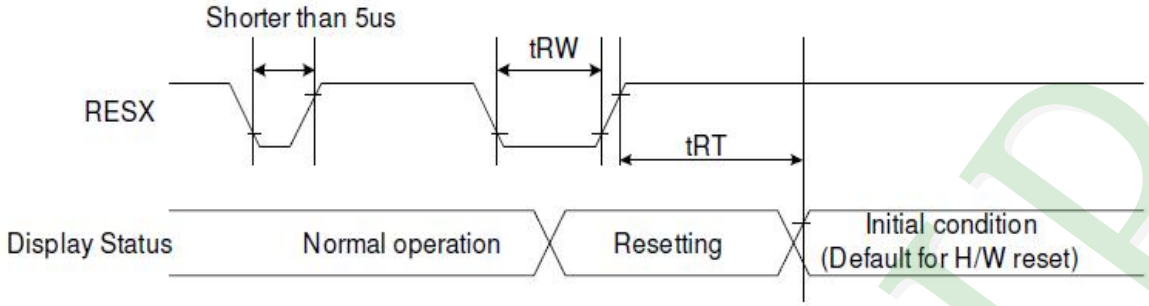
Parallel 18/16/6-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	18/16-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{PCS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level period	15	-	ns	
	PWDL	DOTCLK low-level period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	100	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	6-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{PCS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level pulse period	15	-	ns	
	PWDL	DOTCLK low-level pulse period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	100	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

Note: Ta = -30 to 70 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

Reset Timing



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
				120 (note 1,6,7)	mS

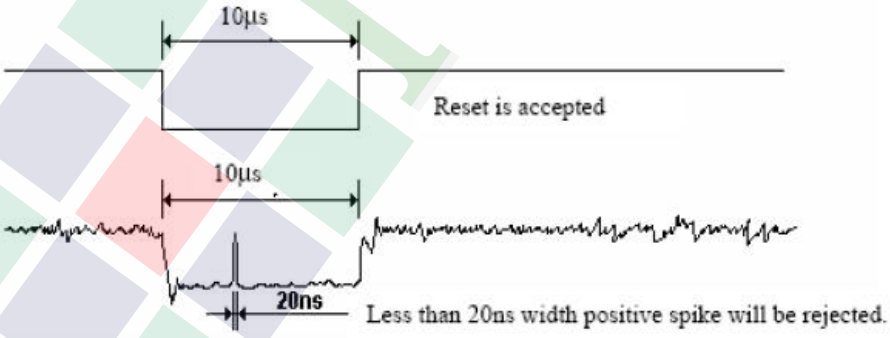
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:



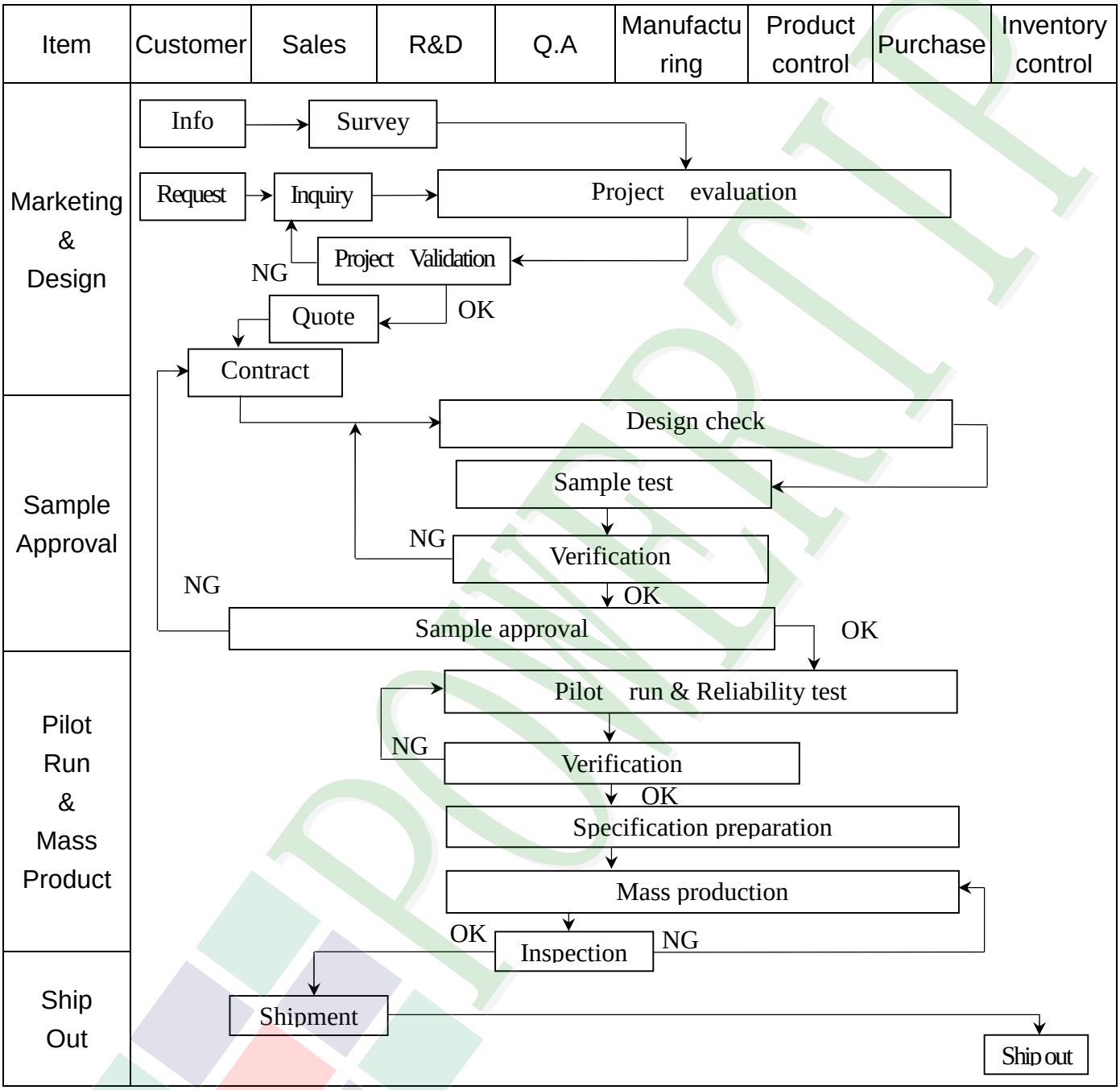
Note 5: When Reset applied during Sleep In Mode.

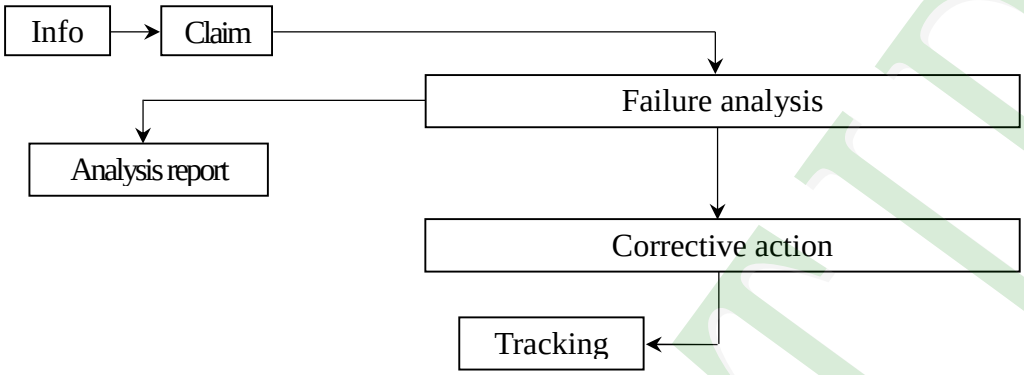
Note 6: When Reset applied during Sleep Out Mode.

Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart



Item	Customer	Sales	R&D	Q.A	Manufacturing	Product control	Purchase	Inventory control
Sales Service								
Q.A Activity	1. ISO 9001 Maintenance Activities 2. Process improvement proposal 3. Equipment calibration 4. Education And Training Activities 5. Standardization Management							

3.2 Inspection Specification

◆Scope ：The document shall be applied to TFT-LCD Module for less than 3.5″ (Ver.B01).

◆Inspection Standard：MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

◆Equipment：Gauge、MIL-STD、Powertip Tester、Sample

◆Defect Level：Major Defect AQL： 0.4 ； Minor Defect AQL： 1.5

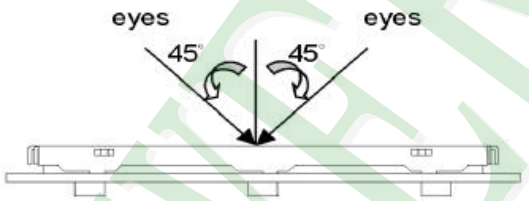
◆OUT Going Defect Level：Sampling.

◆Standard of the product appearance test：

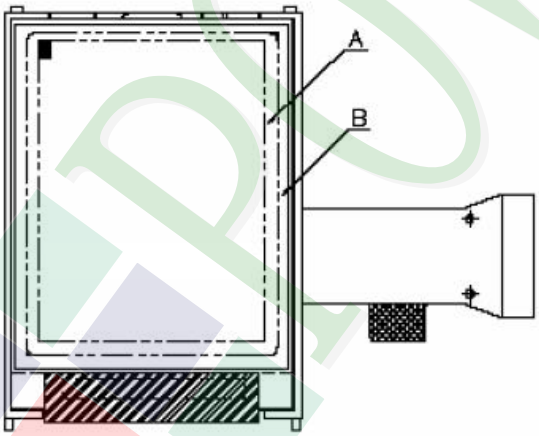
a. Manner of appearance test：

(1). The test best be under 20W×2 fluorescent light，and distance of view must be at 30 cm.

(2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area：viewing area

B area：Outside of viewing area

(4). Standard of inspection： (Unit：mm)

◆Specification For TFT-LCD Module Less Than 3.5″ : (Ver.B01)

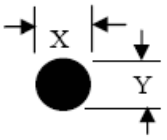
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>Level</th></tr>
<tr><td rowspan="3">01</td><td rowspan="3">Product condition</td><td>1.1 The part number is inconsistent with work order of production.</td><td>Major</td></tr>
<tr><td>1.2 Mixed product types.</td><td>Major</td></tr>
<tr><td>1.3 Assembled in inverse direction.</td><td>Major</td></tr>
<tr><td>02</td><td>Quantity</td><td>2.1 The quantity is inconsistent with work order of production.</td><td>Major</td></tr>
<tr><td>03</td><td>Outline dimension</td><td>3.1 Product dimension and structure must conform to structure diagram.</td><td>Major</td></tr>
<tr><td rowspan="5">04</td><td rowspan="5">Electrical Testing</td><td>4.1 Missing line character and icon.</td><td>Major</td></tr>
<tr><td>4.2 No function or no display.</td><td>Major</td></tr>
<tr><td>4.3 Display malfunction.</td><td>Major</td></tr>
<tr><td>4.4 LCD viewing angle defect.</td><td>Major</td></tr>
<tr><td>4.5 Current consumption exceeds product specifications.</td><td>Major</td></tr>
<tr><td>05</td><td>Dot defect

(Bright dot、Dark dot)

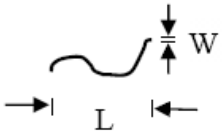
On -display</td><td>
<table>
<tr><th colspan="2">Item</th><th>Acceptance (Q'ty)</th></tr>
<tr><td rowspan="4">Dot Defect</td><td>Bright Dot</td><td>≦ 2</td></tr>
<tr><td>Dark Dot</td><td>≦ 3</td></tr>
<tr><td>Joint Dot</td><td>≦ 2</td></tr>
<tr><td>Total</td><td>≦ 3</td></tr>
</table>
5.1 Inspection pattern：full white , full black , Red , Green and blue screens.
5.2 It is defined as dot defect if defect area ＞1/2 dot.
5.3 The distance between two dot defect ≧5 mm.
</td><td>Minor</td></tr>
</table>

◆Specification For TFT-LCD Module Less Than 3.5″ : (Ver.B01)

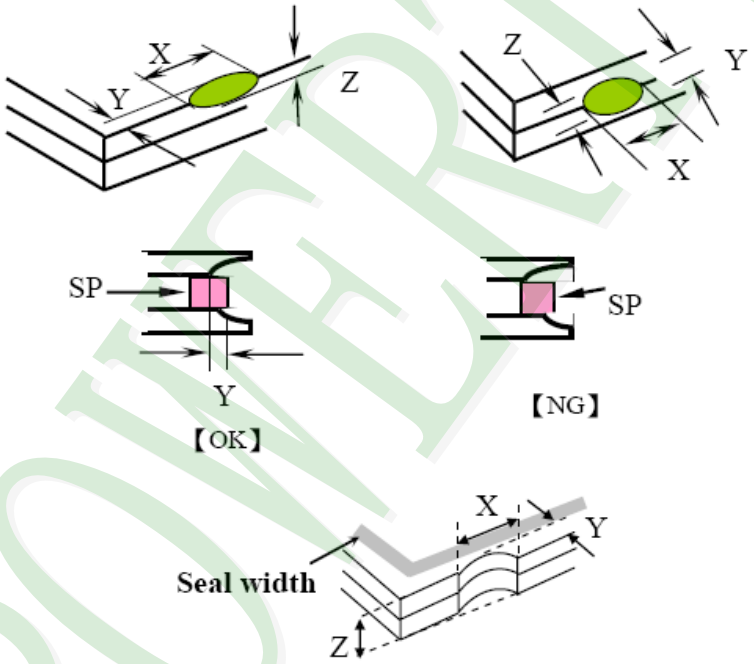
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>Level</th></tr>
<tr><td>06</td><td>Black or white dot、scratch、contamination

Round type
 

Φ=(x+y) / 2

Line type
 
</td><td>6.1 Round type (Non-display or display) :
<table><tr><th rowspan="2">Dimension
(diameter : Φ)</th><th colspan="2">Acceptance (Q'ty)</th></tr><tr><th>A area</th><th>B area</th></tr><tr><td>Φ ≦ 0.15</td><td>Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>0.15 < Φ ≦ 0.20</td><td>2</td></tr><tr><td>0.20 < Φ ≦ 0.30</td><td>2</td></tr><tr><td>Φ > 0.30</td><td>0</td></tr><tr><td>Total</td><td>3</td></tr></table>
6.2 Line type(Non-display or display) :
<table><tr><th colspan="2">Dimension</th><th colspan="2">Acceptance (Q'ty)</th></tr><tr><th>Length (L)</th><th>Width (W)</th><th>A area</th><th>B area</th></tr><tr><td>---</td><td>W ≦ 0.03</td><td>Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>L ≦5.0</td><td>0.03 <W ≦ 0.05</td><td>3</td></tr><tr><td>---</td><td>W >0.05</td><td>As round type</td></tr><tr><td colspan="2">Total</td><td>3</td></tr></table></td><td>Minor</td></tr>
<tr><td>07</td><td>Polarizer Bubble</td><td><table><tr><th rowspan="2">Dimension
(diameter : Φ)</th><th colspan="2">Acceptance (Q'ty)</th></tr><tr><th>A area</th><th>B area</th></tr><tr><td>Φ ≦ 0.20</td><td>Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>0.20 < Φ ≦ 0.50</td><td>3</td></tr><tr><td>Φ > 0.50</td><td>0</td></tr><tr><td>Total</td><td>3</td></tr></table></td><td>Minor</td></tr>
</table>

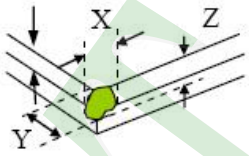
◆Specification For TFT-LCD Module Less Than 3.5″ : (Ver.B01)

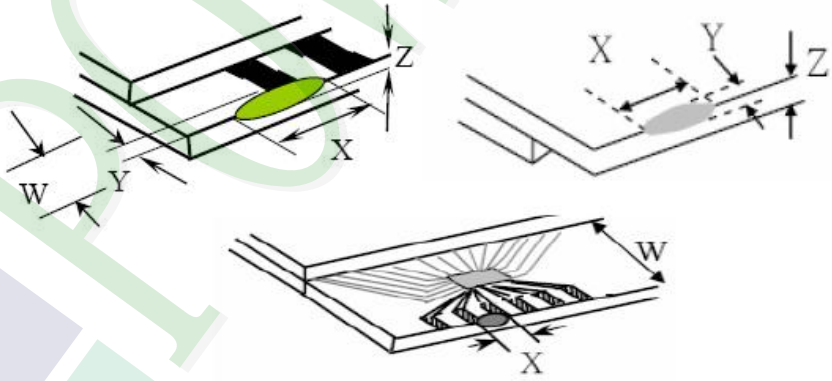
NO	Item	Criterion	Level
08	The crack of glass	Symbols : X : The length of crack Y : The width of crack. Z : The thickness of crack W : terminal length t : The thickness of glass a : LCD side length 8.1 General glass chip : 8.1.1 Chip on panel surface and crack between panels: 	Minor

X	Y	Z
≦ a	Crack can't enter viewing area	≦1/2 t
≦ a	Crack can't exceed the half of SP width.	1/2 t < Z ≦2 t

◆Specification For TFT-LCD Module Less Than 3.5″ : (Ver.B01)

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>Level</th></tr>
<tr><td rowspan="3">08</td><td rowspan="3">The crack of glass</td><td>Symbols :

X : The length of crack
Z : The thickness of crack
t : The thickness of glass
Y : The width of crack.
W : terminal length
a : LCD side length</td><td rowspan="3">Minor</td></tr>
<tr><td>8.1.2 Corner crack :
 

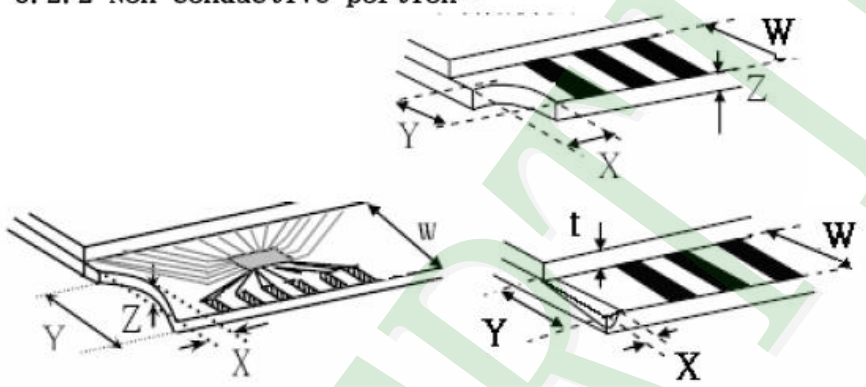
<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>≦1/5 a</td><td>Crack can’t enter viewing area</td><td>Z ≦ 1/2 t</td></tr>
<tr><td>≦1/5 a</td><td>Crack can’t exceed the half of SP width.</td><td>1/2 t < Z ≦ 2 t</td></tr>
</table></td></tr>
<tr><td>8.2 Protrusion over terminal :
8.2.1 Chip on electrode pad :
 

<table>
<tr><th></th><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>Front</td><td>≦ a</td><td>≦ 1/2 W</td><td>≦ t</td></tr>
<tr><td>Back</td><td>≦ a</td><td>≦ W</td><td>≦ 1/2 t</td></tr>
</table></td></tr>
</table>

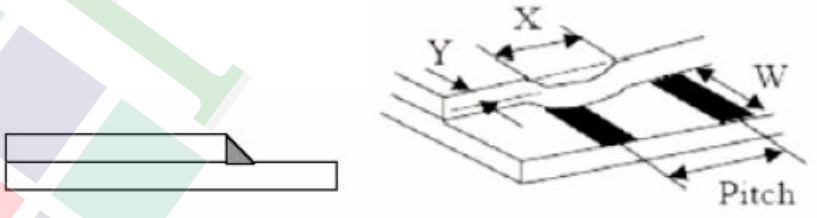
◆Specification For TFT-LCD Module Less Than 3.5″ : (Ver.B01)

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>Level</th></tr>
<tr><td>08</td><td>The crack of glass</td><td>
Symbols :

X : The length of crack　　Y : The width of crack.
Z : The thickness of crack　　W : terminal length
t : The thickness of glass　　a : LCD side length

8.2.2 Non-conductive portion :


<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>≦ 1/3 a</td><td>≦W</td><td>≦t</td></tr>
</table>
⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.

8.2.3 Glass remain :


<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>≦ a</td><td>≦ 1/3 W</td><td>≦t</td></tr>
</table>
</td><td>Minor</td></tr>
</table>

◆Specification For TFT-LCD Module Less Than 3.5″ : (Ver.B01)

NO	Item	Criterion	Level
09	Backlight elements	9.1 Backlight can't work normally.	Major
		9.2 Backlight doesn't light or color is wrong.	Major
		9.3 Illumination source flickers when lit.	Major
10	General appearance	10.1 Pin type、quantity、dimension must match type in structure diagram.	Major
		10.2 No short circuits in components on PCB or FPC .	Major
		10.3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
		10.4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10.5 The folding and peeled off in polarizer are not acceptable.	Minor
		10.6 The PCB or FPC between B/L assembled distance(PCB or FPC) is ≦1.5 mm.	Minor

4. RELIABILITY TEST

4.1 Reliability Test Condition (Ver.B01)

<table>
<tr><th>NO.</th><th>TEST ITEM</th><th>TEST CONDITION</th></tr>
<tr><td>1</td><td>High Temperature Storage Test</td><td>Keep in +80 ±2℃ 96 hrs
Surrounding temperature, then storage at normal condition 4hrs.</td></tr>
<tr><td>2</td><td>Low Temperature Storage Test</td><td>Keep in -30 ±2℃ 96 hrs
Surrounding temperature, then storage at normal condition 4hrs.</td></tr>
<tr><td>3</td><td>High Temperature / High Humidity Storage Test</td><td>Keep in +60 ℃ / 90% R.H duration for 96 hrs
Surrounding temperature, then storage at normal condition 4hrs.
(Excluding the polarizer)</td></tr>
<tr><td>4</td><td>Temperature Cycling Storage Test</td><td>-30℃ → +25℃ → +80℃ → +25℃
(30mins) (5mins) (30mins) (5mins)
10 Cycle
Surrounding temperature, then storage at normal condition 4hrs.</td></tr>
<tr><td rowspan="2">5</td><td rowspan="2">ESD Test</td><td>Air Discharge:
Apply 2 KV with 5 times
Discharge for each polarity +/-
Contact Discharge:
Apply 250 V with 5 times
discharge for each polarity +/-</td></tr>
<tr><td>1. Temperature ambiance : 15℃～35℃
2. Humidity relative : 30%～60%
3. Energy Storage Capacitance(Cs+Cd) : 150pF±10%
4. Discharge Resistance(Rd) : 330Ω±10%
5. Discharge, mode of operation :
Single Discharge (time between successive discharges at least 1 sec)
(Tolerance if the output voltage indication : ±5%)</td></tr>
<tr><td>6</td><td>Vibration Test (Packaged)</td><td>1. Sine wave 10～55 Hz frequency (1 min/sweep)
2. The amplitude of vibration :1.5 mm
3. Each direction (X、Y、Z) duration for 2 Hrs</td></tr>
<tr><td>7</td><td>Drop Test (Packaged)</td><td><table><tr><th>Packing Weight (Kg)</th><th>Drop Height (cm)</th></tr><tr><td>0 ~ 45.4</td><td>122</td></tr><tr><td>45.4 ~ 90.8</td><td>76</td></tr><tr><td>90.8 ~ 454</td><td>61</td></tr><tr><td>Over 454</td><td>46</td></tr></table>Drop Direction :※1 corner / 3 edges / 6 sides each 1time</td></tr>
</table>

5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

5.1.1 If the LCD panel breaks , be careful not to get the liquid crystal to touch your skin.

5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

5.2 HANDLING

5.2.1 Avoid any strong mechanical shock which can break the glass.

5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.

5.2.3 Do not remove the panel or frame from the module.

5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)

5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.

5.2.6 Do not touch the display area with bare hands , this will stain the display area.

5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.

5.2.8 To control temperature and time of soldering is 320±10℃and 3-5 sec.

5.2.9 To avoid liquid (include organic solvent) stained on LCM .

5.3 STORAGE

5.3.1 Store the panel or module in a dark place where the temperature is 25℃ ±5℃ and the humidity is below 65% RH.

5.3.2 Do not place the module near organics solvents or corrosive gases.

5.3.3 Do not crush , shake , or jolt the module.

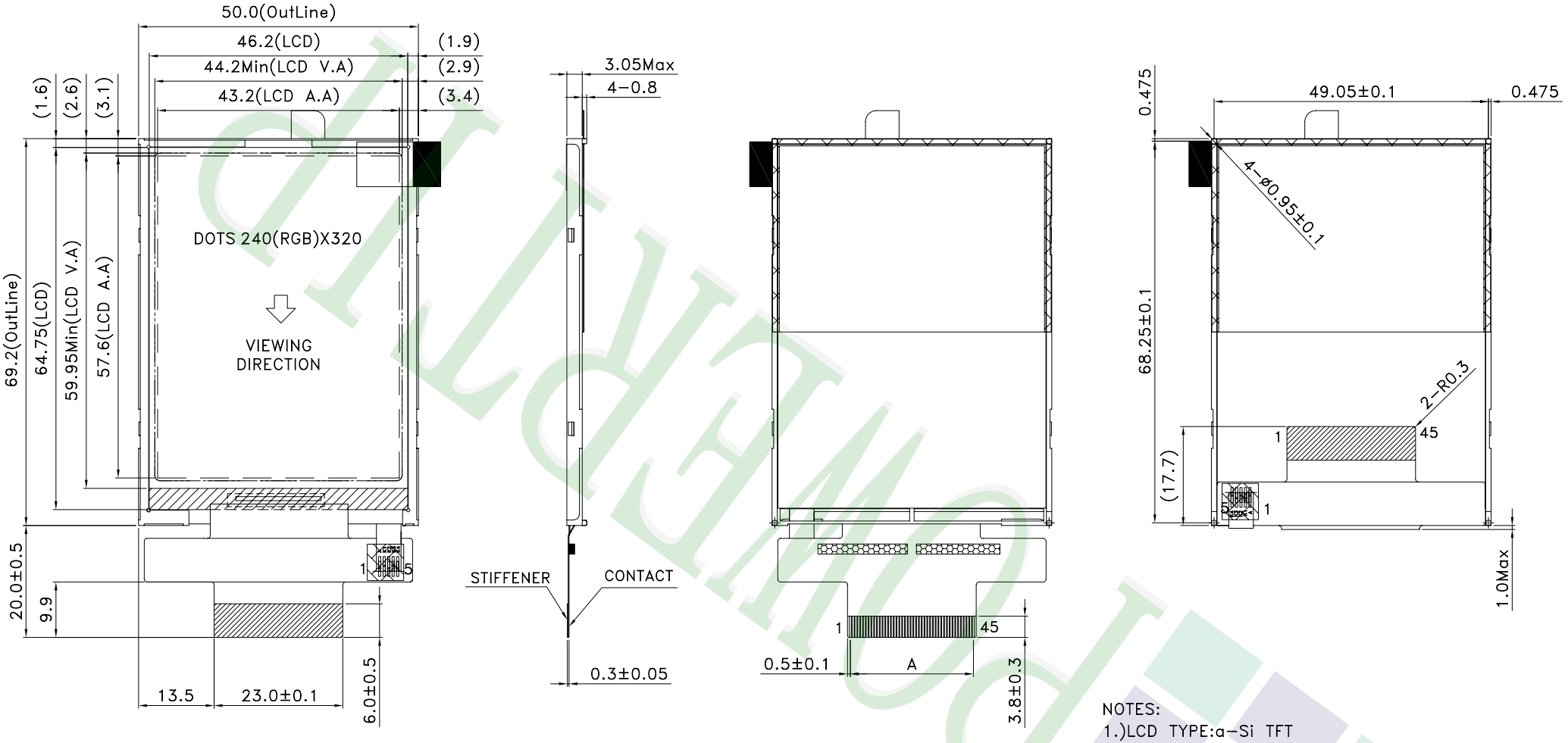
5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment , we cannot take responsibility if the product is used in nuclear power control equipment , aerospace equipment , fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



NOTES:

1.)LCD TYPE:a-Si TFT
2.)LCD DISPLAY: POSITIVE/TRANSMISSIVE
3.)VIEWING DIRECTION:12 O'CLOCK
4.)THE TOLERANCE UNLESS CLASSFIED ±0.3mm
THE R FOR NOT ASSIGNED 0.5±0.1mm
5.)DRIVER IC: ILI9341
6.)A:P0.5X44=22.0±0.05
7.) COMPONENT AREA HEIGHT 1.0 MAX.

REV	REV BY	REVISER	DATE
007			
006			
005			
004			
003			
002			
001	NEW DRAWING	Sally	2012/12/26

PART NO: PH240320T-063-L08Q

DRAWING NAME : JLMD-PH240320T-063-L08Q

TITLE: LCD MODULE DRAWING

久正光電股份有限公司
POWERTIP TECHNOLOGY CORPORATION

Design	Sally	(3)	Surface		
Check	Terry	Unit	MM	Material	
		Scale	FIT	Thickness	
Approve	Ryan	Page	1/1	Quantity	

Length(Min) (mm) \ Tolerance \ Precision	Precision Level
1 ~ 4	-
4 ~ 16	-
16 ~ 63	-
63 ~ 250	-
250 ~ 1000	-

Ver.001

Documents NO.	JPKG-PH240320T-063-L08Q

LCM包裝規格書
LCM Packaging Specifications

Approve	Check	Contact
Ryan	Terry	Sally

1.包裝材料規格表 (Packaging Material) : (per carton)

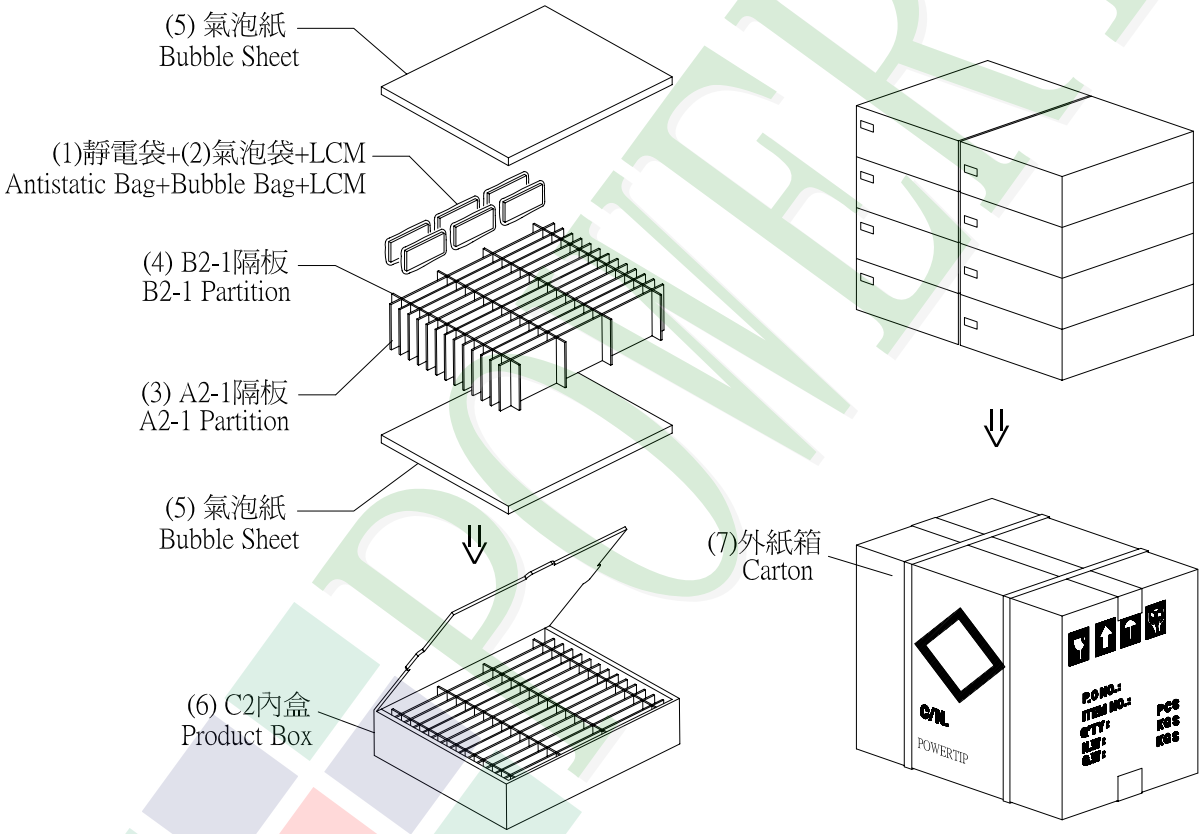
No.	Item	Model	Dimensions (mm)	1Pcs Weight	Quantity	Total Weight
1	成品 (LCM)	PH240320T-063-L08Q	50 X 69.2 X 3.05	0.0137	288	3.9456
2	靜電袋(1)Antistatic Bag	BAG100100ARABA	100 X 100	0.0011	288	0.3168
3	氣泡袋(2)Bubble Bag	BAG100065BWABA	100 X 65	0.0008	288	0.2304
4	A2-1隔板(3)A2-1 Partition	BX29500072BZBA	295 X 72 X 3.0	0.0109	104	1.1336
5	B2-1隔板(4)B2-1 Partition	BX24500072BZBA	245 X 72 X 3.0	0.0094	32	0.3008
6	氣泡紙(5)Bubble Sheet	BAG280240BWABA	280 X 240	0.006	16	0.096
7	C2內盒(6)Product Box	BX31025580AABA	310 X 255 X 86	0.16	8	1.28
8	外紙箱(7)Carton	BX52732536CCBA	527 X 325 X 360	0.83	1	0.83
9						

2.一 整箱總重量 (Total LCD Weight in carton) : 8.24 Kg±10%

3.單箱數量規格表 (Packaging Specifications and Quantity) :

(1)Quantity Of Spacer : A2-1隔板 X 13 , B2-1隔板 X 4

(2)Total LCM quantity in carton : quantity per box 36 x no of boxes 8 = 288



特 記 事 項 (REMARK)

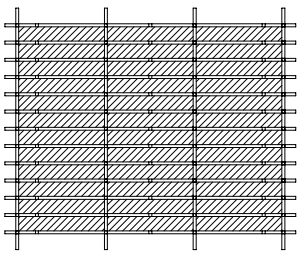
4. Label Specifications :

TYPE			
ID.NO		S/O	
Q'TY	Pcs	Date	
Lot.NO			
Note			

參照"成品包裝點檢作業標準書"內容

5. LCM排放示意圖(前後間隔不放置):

5. LCM placed as figure showing:
(First and last slot should be empty)



模組(LCM) X 1pcs.